

Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute	Tersion.	_
Sectionals *	Material Info	Subsectionals *	A-D
	Manufacturing Info		* : Required Field

Supplier Information								
Company Name *	STMicroelectronics	Response Date *	2018-09-02					
Company Unique ID	NL 008751171B01							
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section					
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section					
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION					
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section					
Supplier Comment		rer to Supplier Comment section Representative Email * Refer to Supplier Comment section						

Uncertainty Statement

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Legal	Statement
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Supplier Acceptance * true Legal Declaration * Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product								
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date				
STM8AL3LE8ATCX	U51S*79KX11Z	А	959	2018-09-02				
	Amount	UoM	Unit type	ST ECOPACK Grade				
	645.00	mg	Each	ECOPACK® 2				
		ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retarda (in each organic material)						

Manufacturing information								
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles						
3	260	3						
bulk Solder Termination Terminal Plating		Terminal Base Alloy	Comment	life.augmented				
				orddgillolliod				
NAC	Matte Tin	Copper						

Package Designator	Size	Nbr of instances	Shape	
QFP	14x14x1.4	80		
Comment	Package: 1S LQFP 80 14x14x1.4 1 0062	2342		

QueryList: RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015							
	Query Response						
1 - Product(s) meets EU RoHS requirement without any exemptions							
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may							
apply)		FALSE					
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s) FALSE							
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions							
Exemption Id. Description							

QueryList: REACH-12th January 2017							
Query Response							
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH							
CategoryLevel_Name	ppm in product						

Material Composition Declaration: note: Substance present with less 0.001mg will not be declared in this document				Mfr Item Name	U51S*7	79KX11Z			5999999.0	1000002.0		
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	6.688	mg	supplier	die	Silicon (Si)	7440-21-3		6.482	mg	969199	10050
				supplier	metallization	Aluminium (AI)	7429-90-5		0.018	mg	2691	28
				supplier	metallization	Copper (Cu)	7440-50-8		0.060	mg	8971	93
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.007	mg	1047	11
				supplier	metallization	Titanium (Ti)	7440-32-6		0.009	mg	1346	14
				supplier	Passivation	Silicon Nitride	12033-89-5		0.016	mg	2392	25
				supplier	Passivation	Silicon Oxide	7631-86-9		0.096	mg	14354	149
Lead-frame	M-011 Other inorganic materials	130.716	mg	supplier	alloy	Copper (Cu)	7440-50-8		125.749	mg	962000	194960
				supplier	alloy	Nickel (Ni)	7440-02-0		3.921	mg	30000	6080
				supplier	alloy	Silicium (Si)	7440-21-3		0.850	mg	6500	1317
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.196	mg	1500	304
Die Attach	M-011 Other inorganic materials	3.180	mg	supplier	glue or soft solder	Isobornyl Methacrylate	7534-94-3		0.138	mg	43243	213
				supplier	glue or soft solder	Bismaleimide resin	Proprietary		0.120	mg	37838	187
				supplier	glue or soft solder	polymer	Proprietary		1.461	mg	459459	2265
				supplier	glue or soft solder	Silver (Ag)	7440-22-4		1.461	mg	459459	2265
Wires	M-011 Other inorganic materials	2.043	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		2.043	mg	1000000	3168
Encapsulation	M-011 Other inorganic materials	493.696	mg	supplier	Moulding Compound	Solid Epoxy Resin	Proprietary		34.676	mg	70237	53761
				supplier	Moulding Compound	Phenol Resin	Proprietary		24.768	mg	50169	38400
				supplier	Moulding Compound	Silica, vitreous	60676-86-0		426.821	mg	864543	661738
				supplier	Moulding Compound	Carbon-black	1333-86-4		2.477	mg	5017	3840
				supplier	Bismuth/Bismuth Compounds	Bismuth	7440-69-9		4.954	mg	10034	7680
Finishing	M-011 Other inorganic materials	8.678	mg	supplier	connections coating	Tin (Sn)	7440-31-5		8.678	mg	1000000	13454